

**DECLARATION OF JOINT INVENTORS FOR PATENT APPLICATION**

As the below named inventor, I hereby declare that:

My residence, post office address and citizenship are as stated below next to my name.

I believe I am the original, first and joint inventor of the subject matter which is claimed and for which a patent is sought on the invention entitled: Semiconductor Assemblies, Methods of Forming Structures Over Semiconductor Substrates, and Methods of Forming Transistors Associated with Semiconductor Substrates, the specification of which is attached hereto.

I hereby state that I have reviewed and understand the contents of the above-identified specification, including the claims.

I acknowledge the duty to disclose information known to me to be material to patentability as defined in Title 37, Code of Federal Regulations §1.56.

**PRIOR FOREIGN APPLICATIONS:**

I hereby state that no applications for foreign patents or inventor's certificates have been filed prior to the date of execution of this declaration.

I hereby declare that all statements made herein of my own knowledge are true and that all statements made on information and belief are believed to be true; and further that these statements were

EL465677587

made with the knowledge that willful false statements and the like so made are punishable by fine or imprisonment, or both, under Section 1001 of Title 18 of the United States Code and that such willful false statement may jeopardize the validity of the application or any patent issued therefrom.

\* \* \* \* \*

Full name of inventor: **Kevin L. Beaman**

Inventor's Signature: Kevin L. Beaman

Date: 6-16-00

Residence: **Boise, ID**

Citizenship: **US**

Post Office Address: **4402 Redhawk Ave.  
Boise, ID 83716**

\* \* \* \* \*

Full name of inventor: **John T. Moore**

Inventor's Signature: John T. Moore

Date: 6/14/00

Residence: **Boise, ID**

Citizenship: **US**

Post Office Address: **12530 W. Lexus Ct.  
Boise, ID 83713**